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# ALUMINIUM OXIDE PREPARED BY ATOMIC LAYER DEPOSITION IN ORGANIC THIN-FILM TRANSISTORS OPERATING AT 2 V: **COMPARISON WITH UV-OZONE OXIDATION**

#### > INTRODUCTION

Large-area, roll-to-roll fabrication of thin-film circuits demands layer thickness uniformity over large areas. Previously, a 10-nm-thick dry bi-layer dielectric based on aluminium oxide (AIO<sub>x</sub>) prepared by UV-ozone oxidation and n-octylphosphonic acid (C<sub>8</sub>PA) monolayer prepared by vacuum evaporation has been developed for organic thin-film transistors (OTFTs) based on pentacene. Here we compare such OTFTs to similar transistors that incorporate ALD-AIO<sub>x</sub>/C<sub>8</sub>PA bi-layer. In addition, a 12.9-nm-thick ALD-AIO<sub>x</sub> exposed to UV-ozone for 60 minutes was incorporated into OTFTs based on dinaphtho[2,3-b:2',3'-f]thieno[3,2-b]thiophene (DNTT).

### > EXPERIMENT

- Two devices incorporated thin ALD-AlO<sub>x</sub> (12.9 nm) and two used thicker (36.8 nm) ALD-AlO<sub>x</sub>. ALD performed from H<sub>2</sub>O and TMA at 160°C. • Within each pairing, one sample underwent a 2-minute UV-ozone clean prior to C<sub>8</sub>PA assembly and/or pentacene evaporation. All other
- transistor layers were identical to UV-ozone-AlO<sub>x</sub> (9 nm) OTFTs.  $W = 1000 \,\mu\text{m}$  and  $L = 30, 50, 70 \,\text{and} 90 \,\mu\text{m}$ . • In the DNTT OTFTs the ALD-AlO<sub>x</sub> (12.9 nm) layer was exposed to UV-ozone for 60 minutes prior to C<sub>8</sub>PA self-assembly. Source/drain and gate
- contacts are similar to pentacene transistors.



### > CONCLUSIONS

- Leakage current density and capacitance are lower for ALD-AlO<sub>x</sub>; primarily as a result of the thicker layer.
- $C_8$ PA self-assembly is not affected by the AlO<sub>x</sub> layer or by its treatment.
- UV-ozone-AlO<sub>x</sub> leads to the lowest threshold voltage. Other parameters are comparable to OTFTs with ALD-AlO<sub>x</sub>.

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$$I_{D} = \mu C \frac{W}{L} (V_{GS} - V_{t}) V_{DS} \qquad \mu_{lin} = \frac{\partial I_{D}}{\partial V_{GS}} \cdot \frac{1}{C V_{DS}} \frac{W}{L}$$
  

$$P: \quad I_{D} = \mu C \frac{W}{2L} (V_{GS} - V_{t})^{2} \qquad \mu_{sat} = \left(\frac{\partial \sqrt{I_{D}}}{\partial V_{GS}}\right)^{2} \cdot \frac{1}{C \frac{W}{2L}}$$

• DNTT OTFTs show greatly improved transistor performance over pentacene devices; DNTT offers lower threshold voltage and substantially higher mobility.

### > AIMS

- Use atomic layer deposition (ALD) to grow thin layers of AlO<sub>x</sub> for low-voltage OTFTs.
- Compare Al/ALD-AlO<sub>x</sub>/C<sub>8</sub>PA/pentacene/Au and Al/UV-ozone-AlO<sub>x</sub>/C<sub>8</sub>PA/pentacene/Au transistors and metalinsulator-metal (MIM) structures.
- Fabricate Al/ALD-AlO<sub>x</sub>/DNTT/Au and Al/ALD-AlO<sub>x</sub>/C<sub>8</sub>PA/DNTT/Au OTFTs and compare them with pentacene OTFTs.



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